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# Middle Power LED Series 2835

# LM281A



Designed for better Im/\$, Lamps, Down light and Ambient





#### **Features& Benefits**

- 0.5 W class middle-power LED
- Extremely wide viewing angle.
- Standard form factor for design flexibility
- Mid-performance and Mid-efficacy



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## 1. Product Code Information

1	2	3	4	5	6	7	8	9	10	11	12	13	14	15	16	17	18
S	Р	М	w	н	т	2	2	8	F	D	5	В	Α	V	0	S	0

Digit	PKG Information	Code			Specification			
1 2 3	Samsung Package Middle Power	SPM						
4 5	Color	WH	White					
6	Product Version	Т	Initial version	Initial version				
7 8	Form Factor	22	2.8 x 3.5 x 0	2.8 x 3.5 x 0.65 mm; 2 pads				
9	Product	8	LM281A	LM281A				
10	Sorting Current (mA)	F	150 mA	150 mA				
11	Chromaticity Coordinates	D	ANSI Standa	ard				
12	CRI& Sorting Temperature	5	Min. 80 2	25 °C				
13 14	Forward Voltage (V)	ВА	2.9~3.4	Bin Code:	A2 2.9~3.0 A3 3.0~3.1 A4 3.1~3.2 A5 3.2~3.3 A6 3.3~3.4			
15 16	CCT (K)	W0 V0 U0 T0 R0 Q0 P0	2700 3000 3500 4000 5000 5700 6500	Bin Code:	W1, W2, W3, W4, W5, W6, W7, W8, W9, WA, WB, WC, WD, WE, WF, WG V1, V2, V3, V4, V5, V6, V7, V8, V9, VA, VB, VC, VD, VE, VF, VG U1, U2, U3, U4, U5, U6, U7, U8, U9, UA, UB, UC, UD, UE, UF, UG T1, T2, T3, T4, T5, T6, T7, T8, T9, TA, TB, TC, TD, TE, TF, TG R1, R2, R3, R4, R5, R6, R7, R8, R9, RA Q1, Q2, Q3, Q4, Q5, Q6, Q7, Q8, Q9, QA P1, P2, P3, P4, P5, P6, P7, P8, P9, PA S1 S2 S3			

## a) Luminous Flux Bins( $I_F = 150$ mA, $T_s = 25$ °C)

Nominal CCT (K)	CRI (Ra) Min.	Product Code	Flux Bin	Flux Range (Φ <sub>v</sub> , lm)
			S1	51.0 ~ 54.5
2700	80	SPMWHT228FD5BAW0S0	S2	54.5 ~ 58.0
			S3	58.0 ~ 61.5
			S1	52.0 ~ 55.5
3000	80	SPMWHT228FD5BAV0S0	S2	55.5 ~ 59.0
			S3	59.0 ~ 62.5
			S1	53.0 ~ 56.5
3500	80	SPMWHT228FD5BAU0S0	S2	56.5 ~ 60.0
			S3	60.0 ~ 63.5
			S1	55.5 ~ 59.0
4000	80	SPMWHT228FD5BAT0S0	S2	59.0 ~ 62.5
			S3	62.5 ~ 66.0
			S1	57.5 ~ 61.0
5000	80	SPMWHT228FD5BAR0S0	S2	61.0 ~ 64.5
			S3	64.5 ~ 68.0
			S1	56.5 ~ 60.0
5700	80	SPMWHT228FD5BAQ0S0	S2	60.0 ~ 63.5
			S3	63.5 ~ 67.0
			S1	55.5 ~ 59.0
6500	80	SPMWHT228FD5BAP0S0	S2	59.0 ~ 62.5
			S3	62.5 ~ 66.0

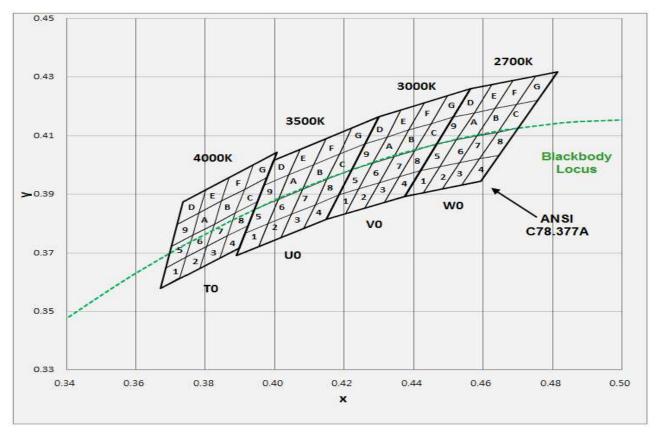
## b) Color Bins ( $I_F = 150$ mA, $T_s = 25$ °C)

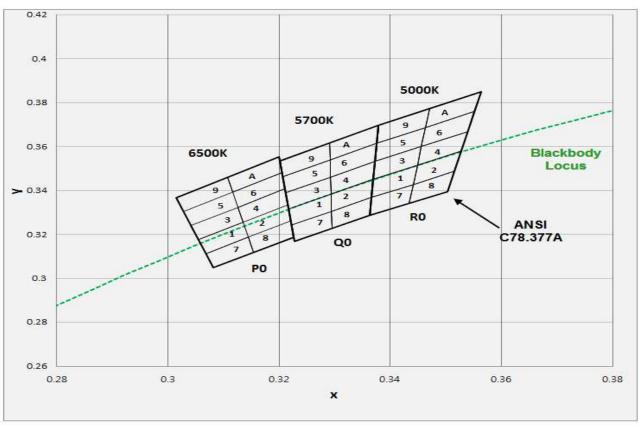
Nominal CCT(K)	CRI (Ra) Min.	Product Code	Color Rank	Chromaticity Bins
2700	80	SPMWHT228FD5BAW0S0	W0 (Whole bin)	W1, W2, W3, W4, W5, W6, W7, W8, W9, WA, WB, WC, WD, WE, WF, WG
3000	80	SPMWHT228FD5BAV0S0	V0 (Whole bin)	V1, V2, V3, V4, V5, V6, V7, V8, V9, VA, VB, VC, VD, VE, VF, VG
3500	3500 80 SPMWHT228FD5B	SPMWHT228FD5BAU0S0	U0 (Whole bin)	U1, U2, U3, U4, U5, U6, U7, U8, U9, UA, UB, UC, UD, UE, UF, UG
4000	80	SPMWHT228FD5BAT0S0	T0 (Whole bin)	T1, T2, T3, T4, T5, T6, T7, T8, T9, TA, TB, TC, TD, TE, TF, TG
5000	80	SPMWHT228FD5BAR0S0	R0 (Whole bin)	R1, R2, R3, R4, R5, R6, R7, R8, R9,RA
5700	80	SPMWHT228FD5BAQ0S0	Q0 (Whole bin)	Q1, Q2, Q3, Q4, Q5, Q6, Q7, Q8, Q9,QA
6500	80	SPMWHT228FD5BAP0S0	P0 (Whole bin)	P1, P2, P3, P4, P5, P6, P7, P8, P9,PA

## c) Voltage Bins (I<sub>F</sub> = 150 mA, T<sub>s</sub> = 25 °C)

Nominal CCT (K)	CRI (Ra) Min.	Product Code	Voltage Rank	Voltage Bin	Voltage Range (V)
				A2	2.9 ~ 3.0
				А3	3.0 ~ 3.1
-	80	SPMWHT228FD5	ВА	A4	3.1 ~ 3.2
				A5	3.2 ~ 3.3
				A6	3.3 ~ 3.4

#### c) Chromaticity Region & Coordinates (I<sub>F</sub> = 150 mA, T<sub>s</sub> = 25 °C)





## c) Chromaticity Region & Coordinates (I<sub>F</sub> = 150 mA, $T_s$ = 25 °C)

Region	CIE x	CIE y	Region	CIE x	CIE y
		W rank	(2700K)		
	0.4373	0.3893		0.4465	0.4071
W1	0.4418	0.3981	W9	0.4513	0.4164
VVI	0.4475	0.3994	vvə	0.4573	0.4178
	0.4428	0.3906		0.4523	0.4085
	0.4428	0.3906		0.4523	0.4085
W2	0.4475	0.3994	10/0	0.4573	0.4178
VVZ	0.4532	0.4008	WA	0.4634	0.4193
	0.4483	0.3919		0.4582	0.4099
	0.4483	0.3919		0.4582	0.4099
MO	0.4532	0.4008	WD	0.4634	0.4193
W3	0.4589	0.4021	WB	0.4695	0.4207
	0.4538	0.3931		0.4641	0.4112
	0.4538	0.3931	WC	0.4641	0.4112
W4	0.4589	0.4021		0.4695	0.4207
VV4	0.4646	0.4034	VVC	0.4756	0.4221
	0.4593	0.3944		0.4700	0.4126
	0.4418	0.3981	WD	0.4513	0.4164
W5	0.4465	0.4071		0.4562	0.4260
VVO	0.4523	0.4085		0.4624	0.4274
	0.4475	0.3994		0.4573	0.4178
	0.4475	0.3994		0.4573	0.4178
W6	0.4523	0.4085	WE	0.4624	0.4274
VVO	0.4582	0.4099	VVE	0.4687	0.4289
	0.4532	0.4008		0.4634	0.4193
	0.4532	0.4008		0.4634	0.4193
W7	0.4582	0.4099	WF	0.4687	0.4289
V V /	0.4641	0.4112	VVF	0.4750	0.4304
	0.4589	0.4021		0.4695	0.4207
	0.4589	0.4021		0.4695	0.4207
1/1/0	0.4641	0.4112	WC.	0.4750	0.4304
W8	0.4700	0.4126	WG	0.4813	0.4319
	0.4646	0.4034		0.4756	0.4221

Region	CIE x	CIE y	Region	CIE x	CIE y
		V rank	(3000K)		
	0.4147	0.3814		0.4221	0.3984
1/4	0.4183	0.3898	V0	0.4259	0.4073
V1	0.4242	0.3919	V9	0.4322	0.4096
	0.4203	0.3833		0.4281	0.4006
	0.4203	0.3833		0.4281	0.4006
1/0	0.4242	0.3919	1/0	0.4322	0.4096
V2	0.4300	0.3939	VA	0.4385	0.4119
	0.4259	0.3853		0.4342	0.4028
	0.4259	0.3853		0.4342	0.4028
1.10	0.4300	0.3939		0.4385	0.4119
V3	0.4359	0.3960	VB	0.4449	0.4141
	0.4316	0.3873		0.4403	0.4049
	0.4316	0.3873		0.4403	0.4049
	0.4359	0.3960	1/0	0.4449	0.4141
V4	0.4418	0.3981	VC	0.4513	0.4164
	0.4373	0.3893		0.4465	0.4071
	0.4183	0.3898	VD	0.4259	0.4073
\ /F	0.4221	0.3984		0.4299	0.4165
V5	0.4281	0.4006		0.4364	0.4188
	0.4242	0.3919		0.4322	0.4096
	0.4242	0.3919		0.4322	0.4096
140	0.4281	0.4006		0.4364	0.4188
V6	0.4342	0.4028	VE	0.4430	0.4212
	0.4300	0.3939		0.4385	0.4119
	0.4300	0.3939		0.4385	0.4119
	0.4342	0.4028		0.4430	0.4212
V7	0.4403	0.4049	VF	0.4496	0.4236
	0.4359	0.3960		0.4449	0.4141
	0.4359	0.3960		0.4449	0.4141
1.00	0.4403	0.4049		0.4496	0.4236
V8	0.4465	0.4071	VG	0.4562	0.4260
	0.4418	0.3981		0.4513	0.4164

## c) Chromaticity Region & Coordinates

Region	CIE x	CIE y	Region	CIE x	CIE y				
		U rank (3500K)							
	0.3889	0.3690		0.3941	0.3848				
114	0.3915	0.3768	110	0.3968	0.3930				
U1	0.3981	0.3800	U9	0.4040	0.3966				
	0.3953	0.3720		0.4010	0.3882				
	0.3953	0.3720		0.4010	0.3882				
110	0.3981	0.3800	110	0.4040	0.3966				
U2	0.4048	0.3832	UA	0.4113	0.4001				
	0.4017	0.3751		0.4080	0.3916				
	0.4017	0.3751		0.4080	0.3916				
110	0.4048	0.3832		0.4113	0.4001				
U3	0.4116	0.3865	UB	0.4186	0.4037				
	0.4082	0.3782		0.4150	0.3950				
	0.4082	0.3782	110	0.4150	0.3950				
	0.4116	0.3865		0.4186	0.4037				
U4	0.4183	0.3898	UC	0.4259	0.4073				
	0.4147	0.3814		0.4221	0.3984				
	0.3915	0.3768	UD	0.3968	0.3930				
	0.3941	0.3848		0.3996	0.4015				
U5	0.4010	0.3882		0.4071	0.4052				
	0.3981	0.3800		0.4040	0.3966				
	0.3981	0.3800		0.4040	0.3966				
110	0.4010	0.3882		0.4071	0.4052				
U6	0.4080	0.3916	UE	0.4146	0.4089				
	0.4048	0.3832		0.4113	0.4001				
	0.4048	0.3832		0.4113	0.4001				
	0.4080	0.3916		0.4146	0.4089				
U7	0.4150	0.3950	UF	0.4222	0.4127				
	0.4116	0.3865		0.4186	0.4037				
	0.4116	0.3865		0.4186	0.4037				
	0.4150	0.3950		0.4222	0.4127				
U8	0.4221	0.3984	UG	0.4299	0.4165				
	0.4183	0.3898		0.4259	0.4073				

Region	CIE x	CIE y	Region	CIE x	CIE y
		T rank	(4000K)		
	0.3670	0.3578		0.3702	0.3722
	0.3726	0.3612	T0	0.3763	0.3760
T1	0.3744	0.3685	T9	0.3782	0.3837
	0.3686	0.3649		0.3719	0.3797
	0.3726	0.3612		0.3763	0.3760
T0	0.3783	0.3646		0.3825	0.3798
T2	0.3804	0.3721	TA	0.3847	0.3877
	0.3744	0.3685		0.3782	0.3837
	0.3783	0.3646		0.3825	0.3798
	0.3840	0.3681		0.3887	0.3836
T3	0.3863	0.3758	ТВ	0.3912	0.3917
	0.3804	0.3721		0.3847	0.3877
	0.3840	0.3681	TO	0.3887	0.3837
	0.3898	0.3716		0.3950	0.3875
T4	0.3924	0.3794	TC	0.3978	0.3958
	0.3863	0.3758		0.3912	0.3917
	0.3686	0.3649	TD	0.3719	0.3797
	0.3744	0.3685		0.3782	0.3837
T5	0.3763	0.3760		0.3802	0.3916
	0.3702	0.3722		0.3736	0.3874
	0.3744	0.3685		0.3782	0.3837
T0	0.3804	0.3721		0.3847	0.3877
T6	0.3825	0.3798	TE	0.3869	0.3958
	0.3763	0.376		0.3802	0.3916
	0.3804	0.3721		0.3847	0.3877
T-7	0.3863	0.3758		0.3912	0.3917
T7	0.3887	0.3836	TF	0.3937	0.4001
	0.3825	0.3798		0.3869	0.3958
	0.3863	0.3758		0.3912	0.3917
T-0	0.3924	0.3794	T-0	0.3978	0.3958
T8	0.3950	0.3875	TG	0.4006	0.4044
	0.3887	0.3836		0.3937	0.4001

## c) Chromaticity Region & Coordinates

Region	CIE x	CIE y	Region	CIE x	CIE y			
R rank (5000K)								
	0.3366	0.3369		0.3456	0.3601			
D.1	0.3441	0.3428	500	0.3539	0.3669			
R1	0.3449	0.3515	R6	0.3551	0.3760			
	0.3369	0.3451		0.3464	0.3688			
	0.3441	0.3428		0.3363	0.3287			
D0	0.3515	0.3487	5-7	0.3433	0.3341			
R2	0.3527	0.3578	R7	0.3441	0.3428			
	0.3449	0.3515		0.3366	0.3369			
	0.3369	0.3451	R8	0.3433	0.3341			
D0	0.3449	0.3515		0.3503	0.3396			
R3	0.3456	0.3601		0.3515	0.3487			
	0.3373	0.3534		0.3441	0.3428			
	0.3449	0.3515		0.3376	0.3616			
D4	0.3527	0.3578	DO	0.3464	0.3688			
R4	0.3539	0.3669	R9	0.3471	0.3775			
	0.3456	0.3601		0.3379	0.3698			
	0.3373	0.3534		0.3464	0.3688			
D.E.	0.3456	0.3601		0.3551	0.3760			
R5	0.3464	0.3688	RA	0.3564	0.3851			
	0.3376	0.3616		0.3471	0.3775			

Region	CIE x	CIE y	Region	CIE x	CIE y					
	Q rank (5700K)									
	0.3222	0.3243		0.3292	0.3461					
04	0.3294	0.3306	00	0.3373	0.3534					
Q1	0.3293	0.3384	Q6	0.3376	0.3616					
	0.3217	0.3316		0.3292	0.3539					
	0.3294	0.3306		0.3227	0.3170					
00	0.3366	0.3369	07	0.3295	0.3228					
Q2	0.3369	0.3451	Q7	0.3294	0.3306					
	0.3293	0.3384		0.3222	0.3243					
	0.3217	0.3316	Q8	0.3295	0.3228					
00	0.3293	0.3384		0.3363	0.3287					
Q3	0.3292	0.3461		0.3366	0.3369					
	0.3212	0.3389		0.3294	0.3306					
	0.3293	0.3384		0.3207	0.3462					
04	0.3369	0.3451	00	0.3292	0.3539					
Q4	0.3373	0.3534	Q9	0.3291	0.3617					
	0.3292	0.3461		0.3202	0.3535					
	0.3212	0.3389		0.3292	0.3539					
OF	0.3292	0.3461		0.3376	0.3616					
Q5	0.3292	0.3539	QA	0.3379	0.3698					
	0.3207	0.3462		0.3291	0.3617					

## c) Chromaticity Region & Coordinates

Region	CIE x	CIE y	Region	CIE x	CIE y	
P rank (6500K)						
	0.3068	0.3113		0.3126	0.3324	
P1	0.3145	0.3187	P6	0.3210	0.3408	
PI	0.3135	0.3256	Po	0.3205	0.3481	
	0.3055	0.3177		0.3117	0.3393	
	0.3145	0.3187		0.3081	0.3049	
P2	0.3221	0.3261	D7	0.3154	0.3119	
P2	0.3216	0.3334	P7	0.3145	0.3187	
	0.3135	0.3256		0.3068	0.3113	
	0.3055	0.3177	P8	0.3154	0.3119	
P3	0.3135	0.3256		0.3226	0.3188	
Po	0.3126	0.3324		0.3221	0.3261	
	0.3041	0.3240		0.3145	0.3187	
	0.3135	0.3256		0.3028	0.3304	
P4	0.3216	0.3334	D0	0.3117	0.3393	
F4	0.3210	0.3408	P9	0.3107	0.3461	
	0.3126	0.3324		0.3015	0.3368	
	0.3041	0.3240		0.3117	0.3393	
D5	0.3126	0.3324	DA	0.3205	0.3481	
P5	0.3117	0.3393	PA	0.3200	0.3554	
	0.3028	0.3304		0.3107	0.3461	

## Note:

Samsung maintains measurement tolerance of Cx, Cy = $\pm 0.005$ 

## 2. Characteristics

## a) Absolute Maximum Rating

ltem	Symbol	Rating	Unit	Condition
Operating Temperature	Ta	-40 ~ +85	°C	-
Storage Temperature	$T_{stg}$	-40 ~ +100	°C	-
LED Junction Temperature	T <sub>j</sub>	110	°C	-
Forward Current	l <sub>F</sub>	150	mA	-
Peak Pulsed Forward Current	l <sub>Fp</sub>	300	mA	Duty 1/10, pulse width 10 ms
Assembly Process Temperature	_	260 <10	°C s	-

## b) Electro-optical Characteristics (I<sub>F</sub> = 150 mA, $T_s$ = 25 °C)

ltem	Unit	Nominal CCT (K)	CRI (R <sub>a</sub> ) Min.	Rank	Bin	Min.	Тур.	Max.
					A2	2.9		3.0
					A3	3.0		3.1
Forward Voltage (V <sub>F</sub> )	V	-	-	ВА	A4	3.1		3.2
					A5	3.2		3.3
					A6	3.3		3.4
			80	W0	S1	51.0		54.5
		2700			S2	54.5		58.0
					S3	58.0		61.5
			80	V0	S1	52.0		55.5
		3000			S2	55.5		59.0
					S3	59.0		62.5
			80	U0	S1	53.0		56.5
		3500			S2	56.5		60.0
					S3	60.0		63.5
					S1	55.5		59.0
Luminous Flux (Φ <sub>ν</sub> )	lm	4000	80	T0	S2	59.0		62.5
					S3	62.5		66.0
		5000	80	R0	S1	57.5		61.0
					S2	61.0		64.5
					S3	64.5		68.0
			80	Q0	S1	56.5		60.0
		5700			S2	60.0		63.5
					S3	63.5		67.0
		6500	80	P0 .	S1	55.5		59.0
					S2	59.0		62.5
					S3	62.5		66.0
Reverse Voltage (@ 10 uA)	V					10.0	_	
Special CRI (R9)	-					0	-	_
Thermal Resistance (junction to solder point)	°C/W					-	24	-
Beam Angle	0					_	120	_

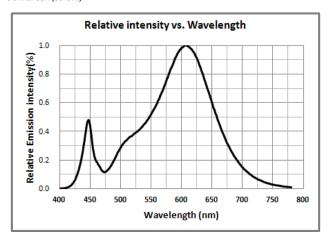
#### Note:

Samsung maintains measurement tolerance of: forward voltage =  $\pm 0.1$  V, luminous flux =  $\pm 5$  %, CRI =  $\pm 3$ , R9 =  $\pm 6.5$ 

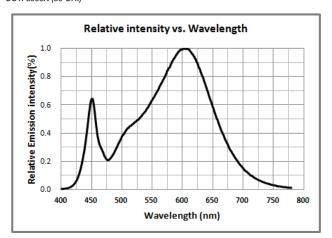
## 3. Typical Characteristics Graphs

#### a) Spectrum Distribution ( $I_F = 150 \text{ mA}, T_s = 25 \,^{\circ}\text{C}$ )

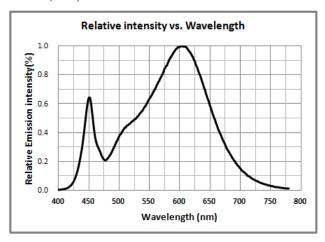
CCT: 2700K (80 CRI)



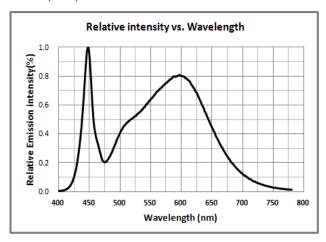
CCT: 3000K (80 CRI)



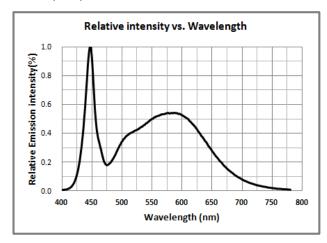
CCT: 3500K (80 CRI)



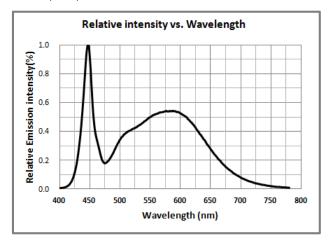
CCT: 4000K (80 CRI)



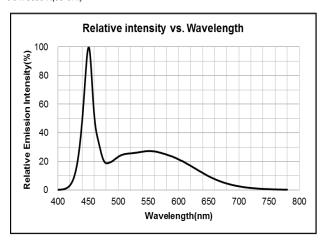
CCT: 5000K (80 CRI)



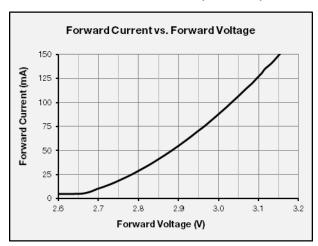
CCT: 5700K (80 CRI)

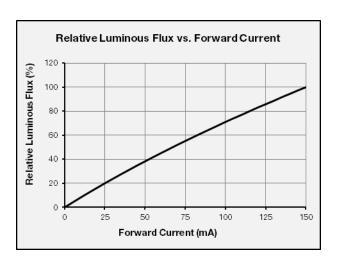


CCT: 6500 K(80 CRI)

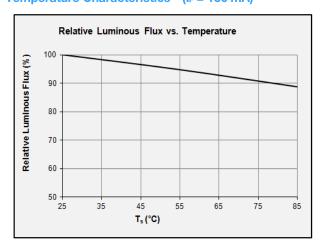


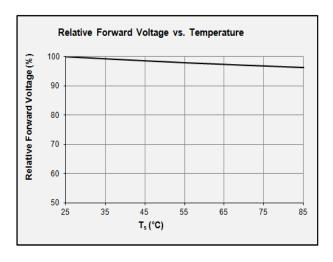
#### b) Forward Current Characteristics (T<sub>s</sub> = 25 °C)



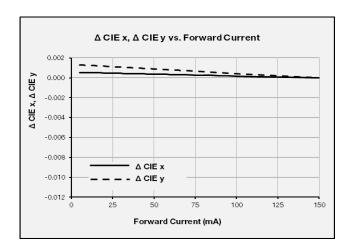


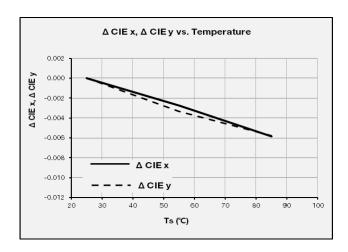
#### c) Temperature Characteristics (I<sub>F</sub> = 150 mA)



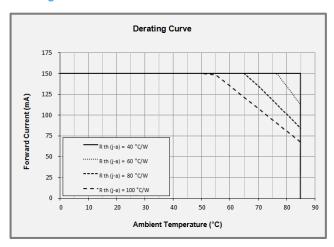


#### d) Color Shift Characteristics ( $T_s = 25$ °C, $I_F = 150$ mA)

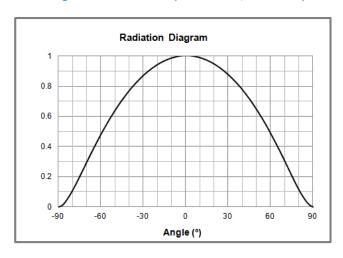




#### e) Derating Curve

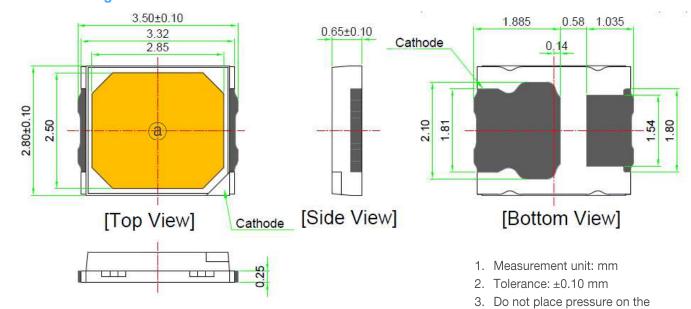


## f) Beam Angle Characteristics ( $I_F = 150$ mA, $T_s = 25$ °C)

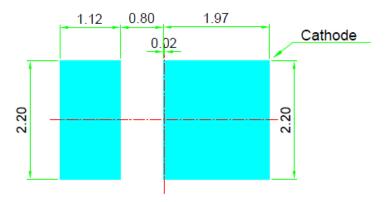


encapsulation resin @

#### 4. Outline Drawing & Dimension



## [RECOMMENDED PCB SOLDER PAD]



#### Notes:

- 1) T<sub>s</sub> point and measurement method:
  - (1) Measure one point at the cathode pad. If necessary, remove PSR of PCB to reach T<sub>s</sub> point.
  - ②All pads must be soldered to the PCB to dissipate heat properly, otherwise the LED can be damaged.

#### **Precautions:**

- 1) Pressure on the LEDs will influence to the reliability of the LEDs. Precautions should be taken to avoid strong pressure on the LEDs. Do not put stress on the LEDs during heating.
- 2) Re-soldering should not be done after the LEDs have been soldered. If re-soldering is unavoidable, LED's characteristics should be carefully checked before and after such repair.
- 3) Do not stack assembled PCBs together. Since materials of LEDs is soft, abrasion between two PCB assembled with LED might cause catastrophic failure of the LEDs.

## 5. Reliability Test Items & Conditions

## a) Test Items

Test Item	Test Condition	Test Hour/Cycle	Sample Size
Room Temperature Life Test	25 °C, DC 150 mA	1000 h	22
High Temperature Life Test	85 °C, DC 150 mA	1000 h	22
High Temperature Humidity Life Test	85 °C, 85 % RH, DC 150 mA	1000 h	22
Low Temperature Life Test	-40 °C, DC 150 mA	1000 h	22
Powered Temperature Cycle Test	$-45^{\circ}\text{C}$ / 20 min ↔ 85 $^{\circ}\text{C}$ / 20 min, sweep 100 min cycle on/off: each 5 min, DC 150 mA	1000 h	22
Thermal Cycles	-45 °C / 15 min ↔ 125 °C / 15 min → Hot plate 180 °C	500 cycles	100
High Temperature Storage	120 °C	1000 h	11
Low Temperature Storage	-40 °C	1000 h	11
ESD (HBM)	R <sub>1</sub> : 10 MΩ R <sub>2</sub> : 1.5 kΩ C: 100 pF V: ±2 kV	5 times	30
Vibration Test	20~2000~20 Hz, 200 m/s², sweep 4 min X, Y, Z 3 direction, each 1 cycle	4 cycles	11
Mechanical Shock Test	1500 g, 0.5 ms 3 shocks each X-Y-Z axis	5 cycles	11

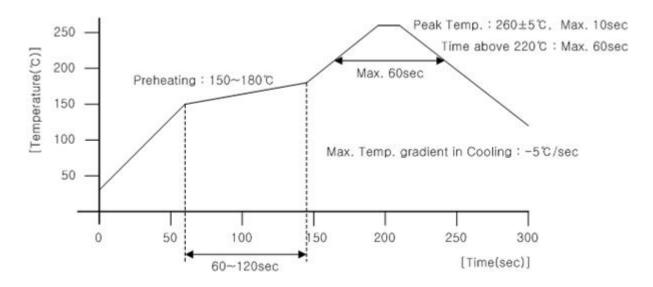
## b) Criteria for Judging the Damage

ltem	Cumbol	Test Condition	Limit			
Item	Symbol	(T <sub>s</sub> = 25 °C)	Min.	Max.		
Forward Voltage	$V_{F}$	$I_F = 150 \text{ mA}$	Init. Value * 0.9	Init. Value * 1.1		
Luminous Flux	Фи	I <sub>F</sub> = 150 mA	Init. Value * 0.7	Init. Value * 1.1		

## 6. Soldering Conditions

## a) Reflow Conditions (Pb free)

Reflow frequency: 2 times max.



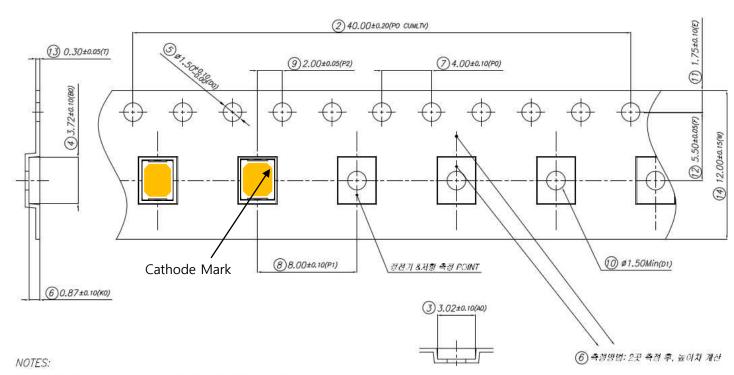
## b) Manual Soldering Conditions

Not more than 5 seconds @max. 300 °C, under soldering iron.

#### 7. Tape & Reel

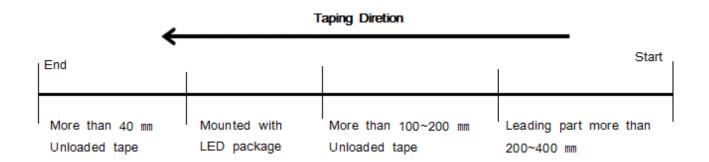
#### a) Taping Dimension

(unit: mm)

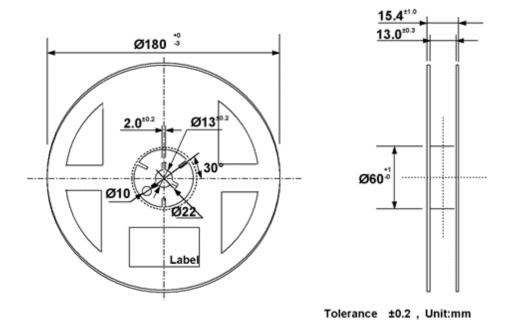


- 1. 10 sprocket hole pitch cumulative tolerance ±0.2
- Camber not to exceed 1mm in 250mm
   Material: Black conductive Polystyrene
- 4. Ko measured from a plane on the inside bottom of the
- pocket to the top surface of the carrier.

  5. Pocket position relative to sprocket hole measured as true position of pocket, not pocket hole.
- 6. Pocket center and pocket hole center must be same position.
- 7. Surface resistivity: MAX 10E+7 OHMS/SQ



#### b) Reel Dimension

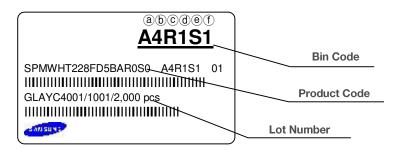


#### Notes:

- 1) Quantity: The quantity/reel is 2,000 pcs
- 2) Cumulative tolerance: Cumulative tolerance / 10 pitches is  $\pm 0.2$  mm
- 3) Adhesion strength of cover tape: Adhesion strength is 0.1-0.7 N when the cover tape is turned off from the carrier tape at 10° angle to the carrier tape
- 4) Packaging: P/N, Manufacturing data code no. and quantity are indicated on the aluminum packing bag

#### 8. Label Structure

#### a) Label Structure



Note: Denoted bin code and product code above is only an Sample

'★' means all kind of Chromaticity Coordinate Ranks

#### Bin Code:

- (a) b:Forward Voltage bin(refer to page 6)
- ©d: Chromaticity bin (refer to page 7~11)
- (refer to page 4)

#### b) Lot Number

The lot number is composed of the following characters:

## 

123456789 / 1abc / 4,000 pcs

1) : Production site (S: Giheung, Korea, G: Tianjin, China)

2 : L (LED)

③ : Product state (A: Normal, B: Bulk, C: First Production, R: Reproduction, S: Sample)

(4) : Year (Z: 2015, A: 2016, B: 2017...)

(5) : Month (1~9, A, B, C)(6) : Day (1~9, A, B~V)

(7)(8)(9) : Product serial number (001 ~ 999)

(a) b) c : Reel number (001 ~ 999)

#### 9. Packing Structure

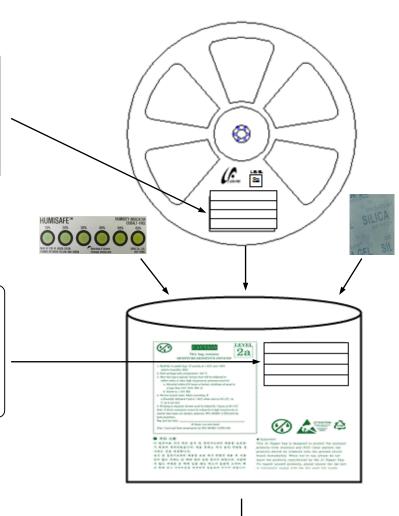
#### a) Packing Process



## **A4R1S1**

Aluminum Vinyl Packing Bag

## **A4R1S1**



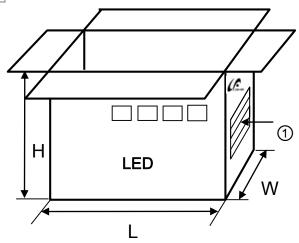
#### **Outer Box**

Material: Paper (SW3B(B))

Tymo		Note		
Туре	L	W	Н	Note
7 inch L	245± 5	220± 5	182± 5	Up to 10reels
7 inch S	245 ± 5	220 ± 5	86 ± 5	Up to 5 reels

#### 1 Side Label

## **A4R1S1**



#### b) Aluminum Vinyl Packing Bag



## CAUTION

# 2a

## This bag contains MOISTURE SENSITIVE DEVICES

- Shelf life in sealed bag: 12 months at <40°C and <90% relative humidity (RH)
- 2. Peak package body temperature: 240 °C
- After this bag is opened, devices that will be subjected to reflow solder or other high temperature processes must be:
  - a. Mounted within 672 hours at factory conditions of equal to or less than 30°C /60% RH, or
  - b. Stored at < 10% RH
- Devices require bake, before mounting, if:

   a. Humidity Indicator Card is > 60% when read at 23±5°C, or
   b. 2a is not met.
- 5. If baking is required, devices must be baked for 10 ~ 24 hours at 60±5°C Note: if device containers cannot be subjected to high temperature or shorter bake times are desired, reference IPC/JEDEC J-STD-033 for bake procedure,

Bag seal due date:

(f blank, see code label)

Note: Level and body temperature by IPC/JEDEC J-STD-020

#### ■ 주의 사항

이 알루미늄 지퍼 백은 습기 및 정전기로부터 제품을 보호하 기 위하여 제작되었습니다. 개봉 후에는 즉시 솔더 작업을 실 시하는 것을 권장합니다.

습기 및 정전기로부터 제품을 보호 하기 위해서 개봉 후 사용 하지 않는 자재는 본 팩에 넣어 보관 하시기 바랍니다. 사용하 지 않는 자재를 본 팩에 넣을 때는 반드시 동봉된 드라이 팩 과 함께 넣고 지퍼부분을 완전하게 밀봉하여 주시기 바랍니다.

## **A4R1S1**

GLAYC4001/1001/2,000 pcs







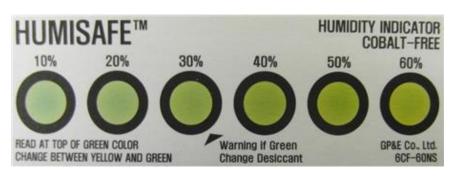


#### ■ Important

This Al Zipper bag is designed to protect the enclosed products from moisture and ESD. Once opened, the products should be soldered onto the printed circuit board immediately. When not in use, please do not leave the products unprotected by the Al Zipper Bag. To repack unused products., please ensure the zip-lock is completely sealed with the dry pack left inside.

#### c) Silica Gel & Humidity Indicator Card inside Aluminum Vinyl Bag





#### 10. Precautions in Handling & Use

- For over-current-proof function, customers are recommended to apply resistors to prevent sudden change of the current caused by slight shift of the voltage.
- 2) This device should not be used in any type of fluid such as water, oil, organic solvent, etc. When washing is required, IPA is recommended to use.
- 3) When the LEDs illuminate, operating current should be decided after considering the ambient maximum temperature.
- 4) LEDs must be stored in a clean environment. If the LEDs are to be stored for three months or more after being shipped from Samsung, they should be packed by a sealed container with nitrogen gas injected (shelf life of sealed bags: 12 months, temperature ~40 °C, ~90 % RH).
- 5) After storage bag is opened, device subjected to soldering, solder reflow, or other high temperature processes must be:
  - a. Mounted within 672 hours (28 days) at an assembly line with a condition of no more than 30 °C / 60 % RH, or
  - b. Stored at <10 % RH
- 6) Repack unused products with anti-moisture packing, fold to close any opening and then store in a dry place.
- 7) Devices require baking before mounting, if humidity card reading is >60 % at  $23 \pm 5 \%$ .
- 8) Devices must be baked for  $10\sim24$  hours at  $60\pm5$  °C, if baking is required.
- 9) The LEDs are sensitive to the static electricity and surge. It is recommended to use a wrist band or anti-electrostatic glove when handling the LEDs. If voltage exceeding the absolute maximum rating is applied to LEDs, it may cause damage or even destruction to LED devices. Damaged LEDs may show some unusual characteristics such as increase in leak current, lowered turn-on voltage, or abnormal lighting of LEDs at low current.
- 10) VOCs (Volatile Organic Compounds) can be generated from adhesives, flux, hardener or organic additives used in luminaires (fixtures). Transparent LED silicone encapsulant is permeable to those chemicals and they may lead a discoloration of encapsulant when they exposed to heat or light. This phenomenon can cause a significant loss of light emitted (output) from the luminaires (fixtures). In order to prevent these problems, we recommend users to know the physical properties of the materials used in luminaires, and they must be selected carefully.
- 11) Risk of sulfurization (or tarnishing)
  - The LED from Samsung Electronics Co., Ltd. uses a silver-plated lead frame and its surface color may change to black (or dark colored) when it is exposed to sulfur (S), chlorine (Cl) or other halogen compound. Sulfurization of lead frame may cause intensity degradation, change of chromaticity coordinates and, in extreme cases, open circuit. It requires caution. Due to possible sulfurization of lead frame, LED should not be used and stored together with oxidizing substances made of materials such as: rubber, plain paper, lead solder cream, etc.
- 12) This LED (Lighting area or Non lighting area) Particle or Dust size under 50,000um2 is permitted.